502752674 04/03/2014

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT2799270

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
HOPHIL LEE	03/25/2014
SEUNGHWAN SONG	03/25/2014
SEUNGBEOM PARK	03/25/2014

RECEIVING PARTY DATA

Name:	LG ELECTRONICS INC.	
Street Address:	128, YEOUI-DAERO, YEONGDEUNGPO-GU	
City:	SEOUL	
State/Country:	KOREA, REPUBLIC OF	
Postal Code:	150-721	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	29486856

CORRESPONDENCE DATA

Fax Number: (202)739-3001

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via

US Mail.

Phone: 202.739.3000

Email: patents@morganlewis.com, ateckman@morganlewis.com

Correspondent Name: ROBERT J. GAYBRICK

Address Line 1: 1111 PENNSYLVANIA AVE, NW

Address Line 4: WASHINGTON, DISTRICT OF COLUMBIA 20004

ATTORNEY DOCKET NUMBER:	001082-7335
NAME OF SUBMITTER:	ROBERT J. GOODELL
SIGNATURE:	/Robert J. Goodell/
DATE SIGNED:	04/03/2014

Total Attachments: 2

source=001082-7335-Assignment#page1.tif source=001082-7335-Assignment#page2.tif

PATENT 502752674 REEL: 032596 FRAME: 0468

Morgan, Lewis & Bockius LLP U.S. Patent & Trademark Office Substitute Form PTO/SB/01 (09-2012)

ATTORNEY DOCKET NO.:
SOLE/JOINT INVENTION
(U.S., Rights Only)

ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

MOBILE PHONE

for which I/WE executed an application for United States Letters Patent concurrently herewith; or the	filed an
application for United States Letters Patent on, (Application No); and	

WHEREAS, LG ELECTRONICS INC., a corporation of Republic of Korea, whose post office address is 128, Yeoui-daero, Yeongdeungpo-gu, Seoul, 150-721, Republic of Korea, (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to issue upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

and Power of Attorney in this application, to the filing date and application	insert here in parenthesis (Application No. on number of said application when known	, filed
IN TESTIMONY WHEREOF, I/WE	have hereunto set our hand(s).	
Full Name of First Assignor Hophil LEE	Assignor's Signature	Date 2014, 3, 25
Address Hangaram Samsung Apt. 208-1503, Burim-dong, Dongan-gu, Anyang-si, Gyeonggi-do, Korea		Citizenship Republic of Korea
Full Name of Second Assignor Seunghwan SONG	Assignor's Signature & & \$1	Date 2014, 3.25
Address Byeollae Ssangyong Yega Apt. 3706-604, Byeollae-dong, Namyangju-si, Gyeonggi-do, Korea		Citizenship Republic of Korea
Names of additional inventors attached Yes	□ No	

AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Declaration

PATENT REEL: 032596 FRAME: 0469

Morgan, Lewis & Bockius LLP U.S. Patent & Trademark Office Substitute Form PTO/SB/01 (09-2012)

Full Name of Third Assignor	Assignor's Signature 1	Date 27
Seungbeom PARK	1000	294.3.26
Address Jungdong Station 2 Cha Purgio Apt. 210-1201, Songnae 2-dong, Sosa-gu, Bucheon-si, Gyeonggi-do, Korea		Citizenship Republic of Korea
Full Name of Fourth Assignor	Assignor's Signature	Date
Address		Citizenship
Full Name of Fifth Assignor	Assignor's Signature	Date
Address		Citizenship
Names of additional inventors attached Yes	⊠ No	

PATENT REEL: 032596 FRAME: 0470

RECORDED: 04/03/2014